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CLAIM AMENDMENTS

- (currently amended) A layer sequence or structure 1 comprising a sequence of layers disposed one on another with: a first highly doped n_a -GaAs layer [[(3)]]; a graded layer [[(5)]] of AlGaAs on the first [[ly]] highly doped layer (3) whereby the and having an aluminum concentration of this layer that diminishes, starting from [[the]] 6 a boundary surface with the first highly doped layer, in the 7 direction of [[the]] an opposite boundary surface of the AlGaAs layer [[(5)]]; [[and]] 9 a second highly doped n'-layer (7), characterized in 10 that; and 11 on at least one boundary layer of the AlGaAs layer 12 [[(5)]] an undoped intermediate layer [[(4,6)]] juxtaposed with the 13 respective highly doped layer (3,7) is provided. 14
 - 2. (currently amended) A layer sequence or structure in accordance with claim 1, characterized in that wherein the undoped intermediate layer is composed of GaAs [[(4,6)]].
- 3. (currently amended) A layer sequence or structure in accordance with claim 1 characterized in that wherein GaAs is the material for the second highly doped n⁺-layer [[(7)]].

- 4. (currently amendment) The layer sequence according to claim 1 characterized in that wherein silicon or tellurium is the doping substance.
- 5. (currently amended) The layer sequence or structure according to claim 1 characterized in that wherein the layer sequence e (3, 4, 5, 6, 7) is arranged on further layers [[(1, 2)]].
- 6. (currently amended) The layer sequence or structure according to claim 1 characterized in that wherein the layer sequence [[(3, 4, 5, 6, 7)]] is disposed on a n-GaAs layer [[(2)]].
- 7. (currently amended) The layer sequence of claim 67

 characterized in that wherein the n-GaAs layer [[(2)]] is disposed

 on a highly doped n'-layer (1), especially of GaAs.
- 8. (currently amended) The layer sequence or structure according to claim 1, characterized in that wherein the first highly doped n_d-GaAs layer (3) and/ or the second highly doped n⁺ layer [[(7)]] are doped with up to 10¹⁸ cm⁻³ silicon.

- (currently amended) A method of making a layer 9. sequence or structure, the method comprising [[with]] the steps of: providing a first highly doped \underline{n}_{d} -GaAs layer (3, 7) is 3 disposed on as a substrate having a pair of opposite boundary surfaces, 5 forming on one of the boundary surfaces of the first 7 highly doped GaAs layer [[(3,7)]] an underdoped undoped GaAs layer (4,6) is arranged and epitaxied epitaxiing the underdoped GaAs 8 <u>layer</u> at an appropriate temperature, 9 providing on the underdoped undoped GaAs layer (4, 6) a 10 graded AlGaAs layer (5) is disposed; and 11 providing on the other of the boundary surfaces a second 12 undoped GaAs layer and epitaxiing the second undoped GaAs layer at 13 an appropriate temperature. 14
 - 10. (canceled)
- 11. (currently amended) [[A]] The method according to
 2 claim 9, characterized in that further comprising the step of
 3 providing a further highly doped GaAs layer (3, 7) is
 4 disposed on the second undoped GaAs layer [[(4, 6)]].

1	12. (currently amended) A layer sequence or structure
2	comprising a series of layers disposed one on another with
3	a first highly doped layer,
4	a graded layer arranged on the first highly doped layer,
5 '	a second highly doped layer, and characterized in that
6	on at least one boundary surface of the graded layer an
7	undoped intermediate layer is arranged and juxtaposed with one of
8	the highly doped layers.